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publication: **11.10.89**(84) Designated contracting
states:(71) Applicant: **NEC CORP**(72) Inventor: **SATO OSAMU**

(74) Representative:

**(54) MANUFACTURE OF
AIR-PROOF SEALING TYPE
SEMICONDUCTOR DEVICE
CONTAINER**

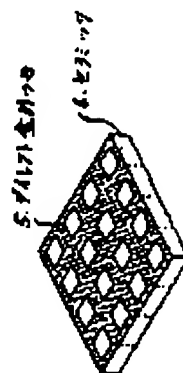
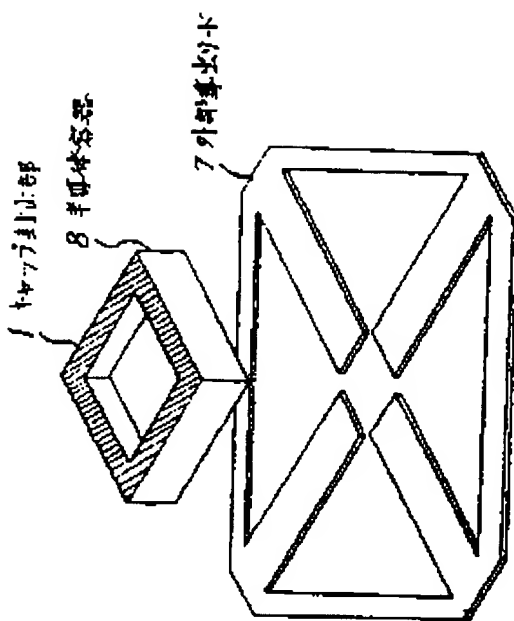
(57) Abstract:

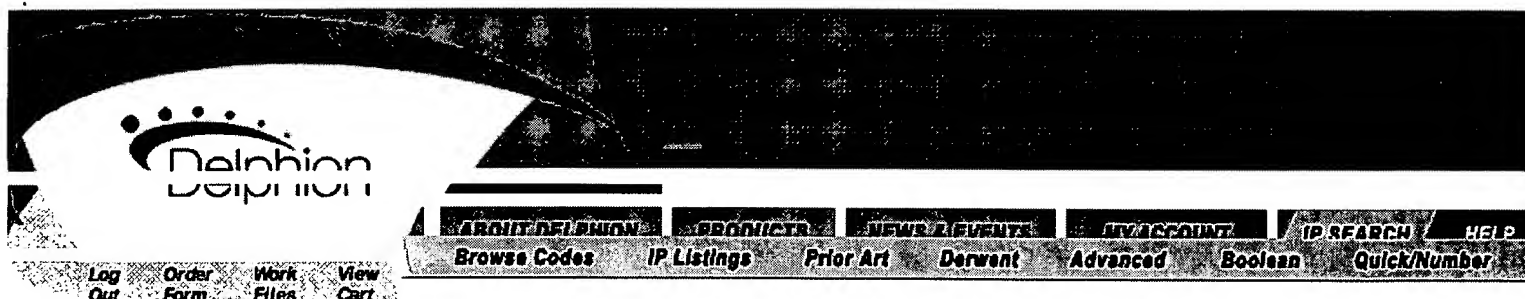
PURPOSE: To save work to install semiconductor containers in a plating jig in the plating procedure after brazing, by plating directly the metallized part of said semiconductor container with gold before brazing an outside drawing lead, etc.

CONSTITUTION: A part composing cap sealing parts 1 of a plurality of semiconductor containers 8 is printed by metallization printing 3 on the face of an alumina sheet 4 and baked, and then the face of the baked metallization layer is directly plated with gold 5. Ceramic 6 is cut into a plurality of semiconductor containers 8 and brazed with a lead 7 by using a material such as silver-copper eutectic solder. After brazing, a current is passed in the lead 7 for nickel plating and gold plating. After plating, the tiebar of the lead 7 is cut off. This saves works to install the containers 8 in a plating tool to enable decreasing the number of

procedures.

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Title: **JP1253941A2: MANUFACTURE OF AIR-PROOF SEALING TYPE SEMICONDUCTOR DEVICE CONTAINER**
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Country: **JP Japan**
 Kind: **A**

Inventor(s): **SATO OSAMU**

Applicant/Assignee: **NEC CORP**
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Issued/Filed Dates: **Oct. 11, 1989 / April 1, 1988**

Application Number: **JP1988000081507**

IPC Class: **H01L 23/02; H01L 23/48**

Priority Number(s): **April 1, 1988 JP1988000081507**

Abstract: **Purpose:** To save work to install semiconductor containers in a plating jig in the plating procedure after brazing, by plating directly the metallized part of said semiconductor container with gold before brazing an outside drawing lead, etc.



Constitution: A part composing cap sealing parts 1 of a plurality of semiconductor containers 8 is printed by metallization printing 3 on the face of an alumina sheet 4 and baked, and then the face of the baked metallization layer is directly plated with gold 5. Ceramic 6 is cut into a plurality of semiconductor containers 8 and brazed with a lead 7 by using a material such as silver-copper eutectic solder. After brazing, a current is passed in the lead 7 for nickel plating and gold plating. After plating, the tiebar of the lead 7 is cut off. This saves works to install the containers 8 in a plating tool to enable decreasing the number of procedures.

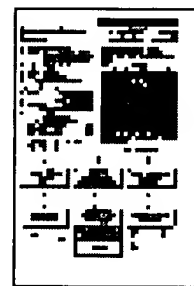
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Other Abstract Info: **DERABS G89-342924 DERG89-342924**

Foreign References: **No patents reference this one**



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